

manufactured, with attributes specific to the wire diameter in use and bonding process parameters.

Wedge tools are manufactured from three main materials:

- Tungsten Carbide for aluminium wire
- Titanium Carbide for gold wire
- Ceramic tipped tungsten carbide tools are also available for gold processes

The figure below describes the Micro Point Pro round wedge nomenclature:



Three main selection criteria for the above wedges are:

Hole Diameter (H): This contributes to bond placement accuracy and wire clearance during looping.

Hole Angle (Ha): This contributes to looping consistency, heel stress in the bonds and tailing consistency.

Bond Length (BL): Directly affects 1st / 2nd bond size, wire pull strength.



For further information about Micro Point Pro bonding tools: https://www.inseto.co.uk/microelectronic-materials-mpp-bonding-tools.php

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